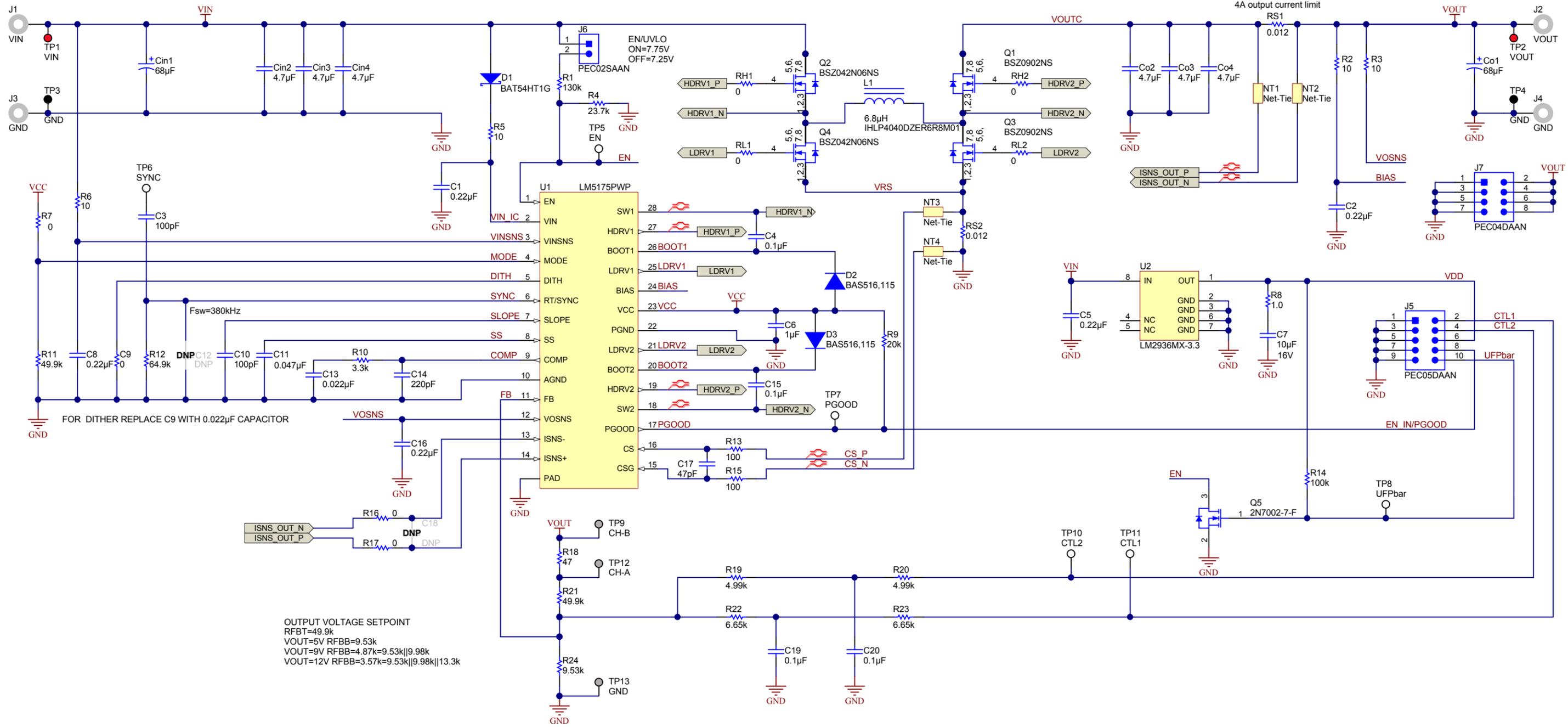


9V to 16V Input, 42V Maximum

5V, 9V or 12V Output @ 3A



Orderable: N/A	Designed for: Public Release	Mod. Date: 8/27/2015
TID #: PMP10624	Project Title: LM5175 Buck Boost	
Number: PMP10624	Rev: A	Sheet Title: Schematic
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 1 of 2
Drawn By: Robert Sheehan	File: PMP10624_REVA_Sh1.SchDoc	Size: B
Engineer: Robert Sheehan	Contact: http://www.ti.com/support	

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Revision History	
Revision	Notes
A	Initial Release

H1 NY PMS 440 0025 PH H2 NY PMS 440 0025 PH H3 NY PMS 440 0025 PH H4 NY PMS 440 0025 PH

H5 1902C H6 1902C H7 1902C H8 1902C

DNP FID1 DNP FID2 DNP FID3

PCB Number: PMP10624
PCB Rev: A

PCB LOGO
Texas Instruments

ZZ1
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ2
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ3
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Orderable: N/A	Designed for: Public Release	Mod. Date: 5/8/2015
TID #: PMP10624	Project Title: LM5175 Buck Boost	
Number: PMP10624	Rev: A	Sheet Title: Hardware
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 2 of 2
Drawn By:	File: PMP10624_REVA_Sh2.SchDoc	Size: B
Engineer: Robert Sheehan	Contact: http://www.ti.com/support	

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